

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT																		
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT																		
<b>CONVEYING PARTY DATA</b>																			
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr><td>Kazuo Takahashi</td><td>03/30/2006</td></tr> <tr><td>Teruo Inaguma</td><td>03/30/2006</td></tr> <tr><td>Junichi Honda</td><td>04/17/2006</td></tr> <tr><td>Koji Suzuki</td><td>03/30/2006</td></tr> <tr><td>Shigeto Watanabe</td><td>03/30/2006</td></tr> <tr><td>Shin Sasaki</td><td>03/30/2006</td></tr> <tr><td>Eiji Nakashio</td><td>03/30/2006</td></tr> <tr><td>Manabu Aizawa</td><td>03/30/2006</td></tr> </tbody> </table>		Name	Execution Date	Kazuo Takahashi	03/30/2006	Teruo Inaguma	03/30/2006	Junichi Honda	04/17/2006	Koji Suzuki	03/30/2006	Shigeto Watanabe	03/30/2006	Shin Sasaki	03/30/2006	Eiji Nakashio	03/30/2006	Manabu Aizawa	03/30/2006
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<b>RECEIVING PARTY DATA</b>																			
<b>Name:</b>	Sony Corporation																		
<b>Street Address:</b>	7-35 Kitashinagawa																		
<b>City:</b>	Shinagawa-Ku, Tokyo																		
<b>State/Country:</b>	JAPAN																		
<b>PROPERTY NUMBERS Total: 1</b>																			
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11368144</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11368144														
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<b>CORRESPONDENCE DATA</b>																			
<b>Fax Number:</b>	(312)876-7934																		
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<b>ATTORNEY DOCKET NUMBER:</b>	09792909-6579																		

OP \$40.00 11368144

**PATENT**

**500106600**

**REEL: 017651 FRAME: 0195**

NAME OF SUBMITTER:

David R. Metzger

Total Attachments: 3

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## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in VIBRATING GYROSENSOR

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/368,144, Filing Date: March 3, 2006.

This assignment executed on the dates indicated below.

<u>Kazuo TAKAHASHI</u>	
Name of first or sole inventor	Execution date of U.S. Patent Application
<u>Miyagi, Japan</u>	
Residence of first or sole inventor	
<u>Kazuo Takahashi</u>	<u>March 30 2006</u>
Signature of first or sole inventor	Date of this assignment

Teruo INAGUMA  
Name of second inventor  
Miyagi, Japan  
Residence of second inventor  
*Teruo Inaguma*  
Signature of second inventor  
Execution date of U.S. Patent Application  
*March 30, 2006*  
Date of this assignment

Junichi HONDA  
Name of third inventor  
Miyagi, Japan  
Residence of third inventor  
*Junichi Honda*  
Signature of third inventor  
Execution date of U.S. Patent Application  
*April 17, 2006*  
Date of this assignment

Koji SUZUKI  
Name of fourth inventor  
Miyagi, Japan  
Residence of fourth inventor  
*Koji Suzuki*  
Signature of fourth inventor  
Execution date of U.S. Patent Application  
*March 30, 2006*  
Date of this assignment

Shigeto WATANABE  
Name of fifth inventor  
Miyagi, Japan  
Residence of fifth inventor  
*Shigeto Watanabe*  
Signature of fifth inventor  
Execution date of U.S. Patent Application  
*March 30, 2006*  
Date of this assignment

Shin SASAKI

Name of sixth inventor

Execution date of U.S. Patent Application

Miyagi, Japan

Residence of sixth inventor

Shin Sasaki

March 30 2006

Signature of sixth inventor

Date of this assignment

Eiji NAKASHIO

Name of seventh inventor

Execution date of U.S. Patent Application

Miyagi, Japan

Residence of seventh inventor

Eiji Nakashio

March 30 2006

Signature of seventh inventor

Date of this assignment

Manabu AIZAWA

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Execution date of U.S. Patent Application

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Residence of eighth inventor

Manabu Aizawa

March 30 2006

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment